## 2SK359

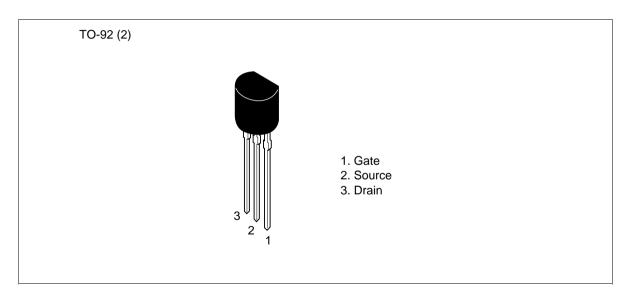
## Silicon N-Channel MOS FET

# **HITACHI**

#### **Application**

VHF amplifier

#### Outline





## 2SK359

### **Absolute Maximum Ratings** (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{DSX}^{*1}$	20	V
Gate to source voltage	$V_{GSS}$	±5	V
Drain current	I <sub>D</sub>	30	mA
Gate current	l <sub>G</sub>	±1	mA
Channel power dissipation	Pch	400	mW
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

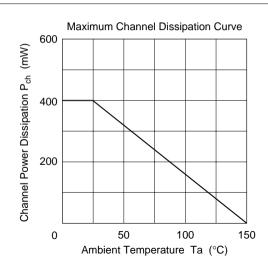
Note: 1.  $V_{GS} = -4 \text{ V}$ 

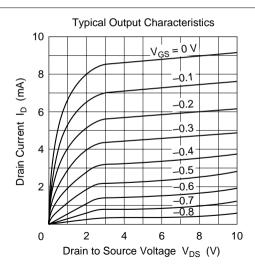
### **Electrical Characteristics** (Ta = 25°C)

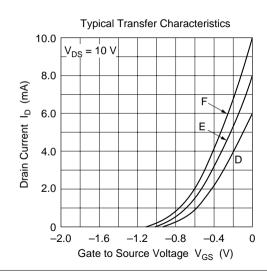
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSX}$	20	_	_	V	$I_D = 100 \ \mu A, \ V_{GS} = -4 \ V$
Gate cutoff current	I <sub>GSS</sub>	_	_	±20	nA	$V_{GS} = \pm 5 \text{ V}, V_{DS} = 0$
Drain current	I <sub>DSS</sub> *1	4		12	mA	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0
Gate to source cutoff voltage	$V_{\text{GS(off)}}$	0	_	-2.0	V	$V_{DS} = 10 \text{ V}, I_{D} = 10  \mu\text{A}$
Forward transfer admittance	y <sub>fs</sub>	8	14	_	mS	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$ f = 1 kHz
Input capacitance	Ciss	_	2.5	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$ f = 1 MHz
Output capacitance	Coss	_	1.6	_	pF	_
Reverse transfer capacitance	Crss	_	0.03	_	pF	_
Power gain	PG	_	30	_	dB	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$ f = 100 MHz
Noise figure	NF	_	2	_	dB	_

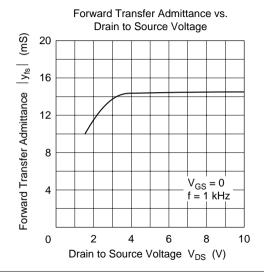
Note: 1. The 2SK359 is grouped by I<sub>DSS</sub> as follows.

D E F 4 to 8 6 to 10 8 to 12









### 2SK359

0.02

0.01

0.5

1.0

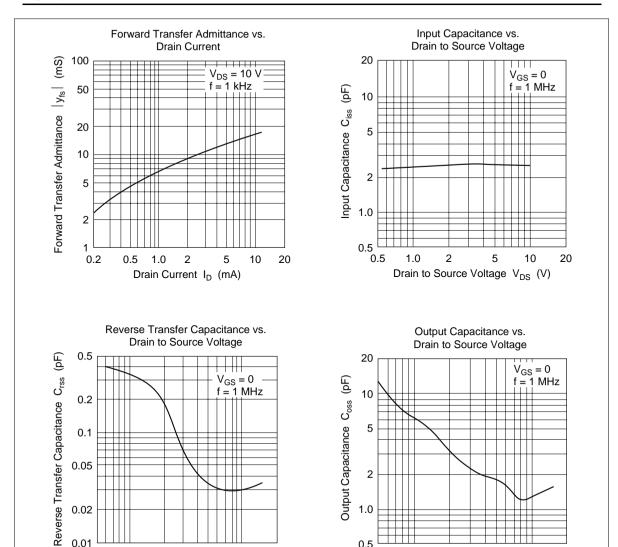
2

5

Drain to Source Voltage  $V_{DS}$  (V)

10

20



1.0

0.5

2

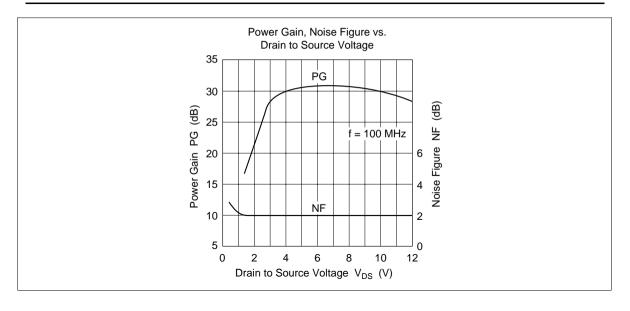
Drain to Source Voltage  $V_{DS}$  (V)

1.0

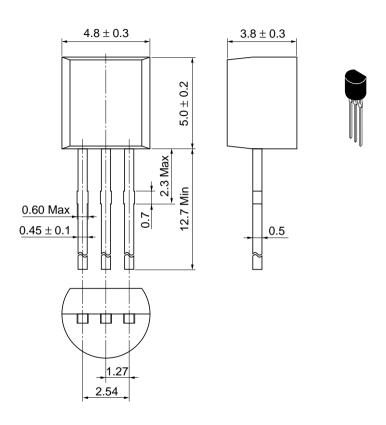
5

10

20



Unit: mm



Hitachi Code	TO-92 (2)
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.25 g

#### **Cautions**

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